



Speaker Biography: Timothy M. Hancock (S'96–M'05–SM'11) received a B.S. degree in electrical engineering from the Rose-Hulman Institute of Technology and M.S. and Ph.D. degrees in electrical engineering from the University of Michigan, where he worked on the development of SiGe integrated microwave circuits from 6 to 77 GHz. From 2005-2016 he was a staff member and later an assistant group leader at MIT Lincoln Laboratory, where he worked on the development of low-power wireless devices, multiple-input-multiple-output (MIMO) communication systems, wideband receiver technology, and GaN on silicon material growth and device process development. Currently Dr. Hancock is serving as a program manager with the Defense Advanced Research Projects Agency (DARPA) in the Microsystems Technology

Office (MTO). Dr. Hancock served for 10 years on the Technical Program Committee of the Radio Frequency Integrated Circuits (RFIC) Symposium and was an active member of the Boston International Microwave Symposium (IMS) Steering Committees in 2009 and 2019. He is a senior member of the IEEE and the 2010 inaugural recipient of the MIT Lincoln Laboratory Early Career Technical Achievement Award.

Title: Application of Heterogenous Integration to Advanced Transceivers and Millimeter Wave Phased Arrays

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